AMENDMENTS TO THE CLAIMS

The following listing of claims will replace all prior versions and listings of claims in the application.

LISTING OF CLAIMS

1. (Currently Amended) A method for manufacturing electron emitters by providing pairs of element electrodes, and conductive layers connecting the element electrodes to each other on a substrate, the method comprising:

a step of forming banks surrounding electrode-forming regions for forming the element electrodes and conductive-layer forming regions for forming the conductive layers;

a step of discharging first droplets toward the electrode-forming regions; and

a step of discharging second droplets toward the conductive-layer forming regions; and

a step of removing the banks.

2. (Original) The method of manufacturing electron emitters according to Claim 1, further comprising a step of lyophobing the banks.

3. (Original) The method of manufacturing electron emitters according to Claim 1, wherein the banks are formed using a lyophobic material.

4. (Original) The method for manufacturing electron emitters according to Claim 1, further comprising a step of lyophilizing at least one of the electrode-forming region and the conductive-layer forming region.

5. (Original) An electron emitter manufactured by the method according to Claim 1.

6. – 8. (Cancelled)

9. (Currently Amended) A method for manufacturing an electron emitter comprising:

defining a pair of spaced apart electrode-forming regions on a substrate;

defining a conductive layer-forming region on the substrate, the conductive layer-forming region interconnecting the electrode-forming regions;

forming a bank encircling the electrode-forming regions and the conductive layer-forming region;

discharging first droplets toward the electrode-forming regions to form a pair of element electrodes; ~~and~~

discharging second droplets toward the conductive layer-forming regions to form a conductive layer connecting the element electrodes to each other; and

removing the bank after the conductive layer and element electrodes are formed.

10. (Previously Presnted) The method of claim 9, further comprising treating a portion of the conductive layer to form an electron-emitting section.

11. (Cancelled)

12. (Previously Presented) The method of claim 9 further comprising rendering the bank lyophobic.

13. (Previously Presented) The method of claim 9 further comprising rendering at least one of:

the electrode-forming regions; and

the conductive layer-forming region;

lyophilic.

14. (new) A method for manufacturing electron emitters by providing pairs of element electrodes, and conductive layers connecting the element electrodes to each other on a substrate, the method comprising:

a step of forming banks surrounding electrode-forming regions for forming the element electrodes and conductive-layer forming regions for forming the conductive layers;

a step of discharging first droplets toward the electrode-forming regions; and

a step of discharging second droplets toward the conductive-layer forming regions; and

a step of lyophobing the banks.

15. (new) The method of manufacturing electron emitters according to Claim 14, wherein the banks are formed using a lyophobic material.

16. (new) The method for manufacturing electron emitters according to Claim 1, further comprising a step of lyophilizing at least one of the electrode-forming region and the conductive-layer forming region.

17. (New) An electron emitter manufactured by the method according to Claim 14.